

AMENDMENTS TO THE SPECIFICATION

Amend the Abstract of the Disclosure to read as follows:

There is provided a sheet peeling apparatus and a peeling method using a plurality of peeling units ~~capable of performing peeling off operation under optimum condition in accordance with the material, thickness or the like of a protective sheet.~~ A sheet peeling apparatus [[10]] for peeling off a sheet [[S]] stuck on the surface of a semiconductor wafer [[W]] by using an adhesive tape [[T]] of a width narrower than that of the sheet [[S]], which is equipped with a peeling head [[15]] ~~(second peeling unit)~~ for peeling off the sheet [[S]] by pulling the adhesive tape [[T]] in an obtuse angled direction in a state stuck to the end portion of the sheet; and first and second rollers 21, 22 ~~(first peeling unit)~~ for peeling off the sheet [[S]] by pulling the adhesive tape [[T]] in the substantially right angle or acute angle direction in a state stuck with the adhesive tape [[T]] in the direction across the sheet [[S]]. Either ~~one~~ of the peeling units are selectively used in accordance with the type of the sheet [[S]].

Application No. 10/577,258
Art Unit: 1791

Amendment under 37 C.F.R. §1.111
Attorney Docket No. 062456

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Please see the attached Substitute Specification, submitted herewith as a marked-up version and a clean version.